

Connector for Memory Stick Micro™

SCNA Series



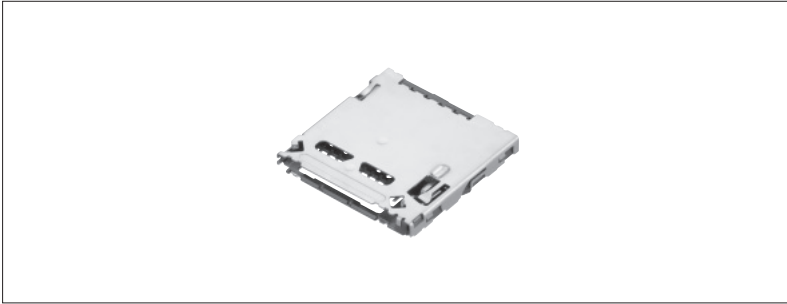
Minimum mounting area for compact devices.

For SD Memory Card

For microSD™ Card

For SIM Card 8pins

For W-SIM



For Memory Stick Micro™

For Memory Stick™

Combine Type

For Compact Flash™

For CMOS Camera Module

Typical Specifications

| Items | | Specifications |
|-------------|----------------------------------|-----------------------|
| Structure | Applicable media | Memory Stick Micro™ |
| | Mounting type | Surface mounting type |
| | Mounting style | Standard mount |
| | Media ejection structure | Push-push type |
| Performance | Operating temperature range | -25 °C to +60 °C |
| | Voltage proof | 250V AC 1minute |
| | Insulation resistance (Initial) | 1,000MΩ min. |
| | Contact resistance (Initial) | 40mΩ max. |
| | Insertion and removal cycle | 12,000cycles |

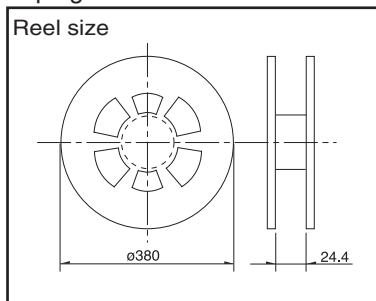
Product Line

| Media ejection structure | Mounting system | Stand-off (mm) | Packing system | Product No. |
|--------------------------|-----------------|----------------|----------------|-------------|
| Push-push type | Standard mount | 0 | Taping | SCNA1A0300 |

Packing Specifications

Taping

Unit:mm



| Number of packages (pcs.) | | | Tape width (mm) | Export package measurements (mm) |
|---------------------------|---------------|------------------------|-----------------|----------------------------------|
| 1 reel | 1 case /Japan | 1 case /export packing | | |
| 1,500 | 4,500 | 9,000 | 24 | 403 × 403 × 249 |



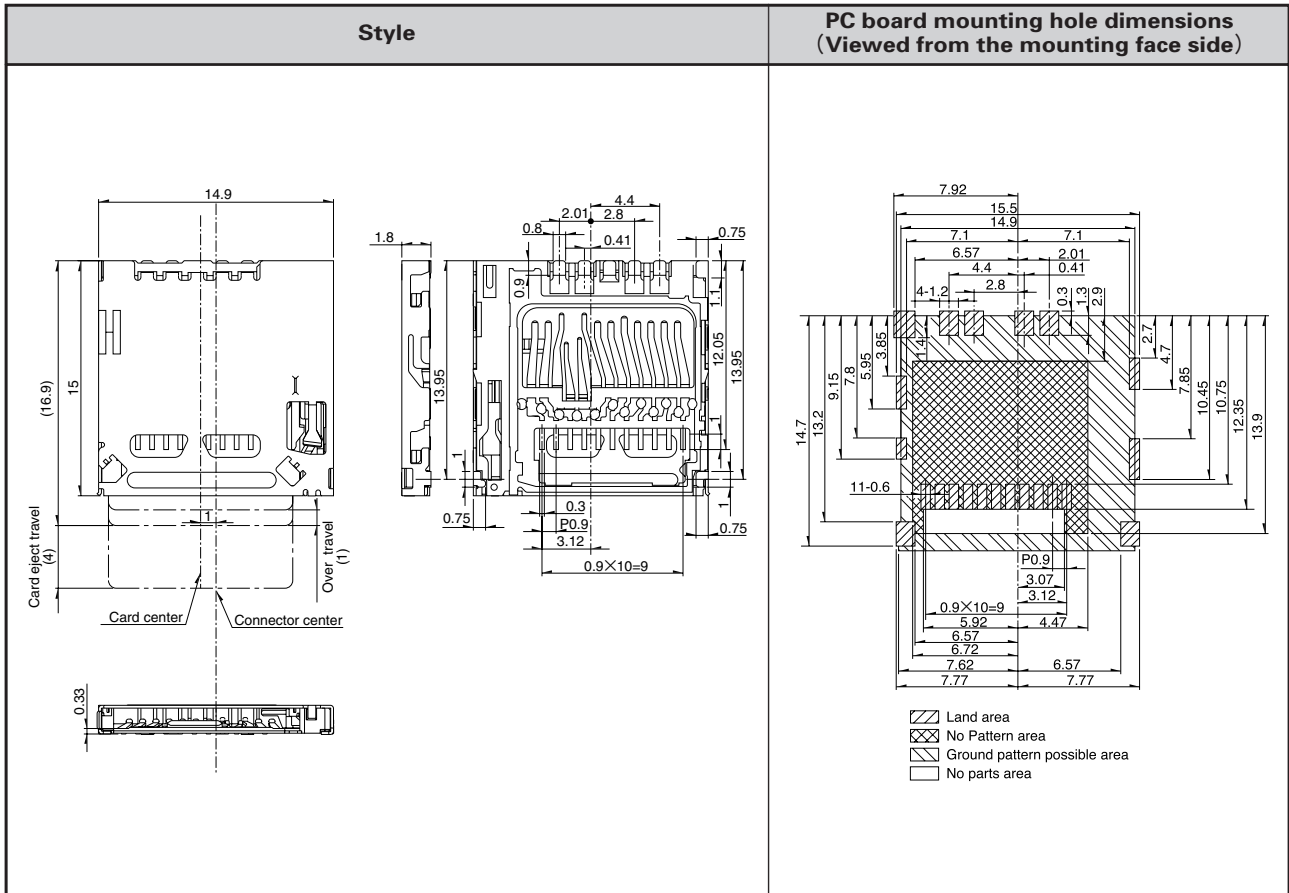
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ALPS

Dimensions

Unit:mm



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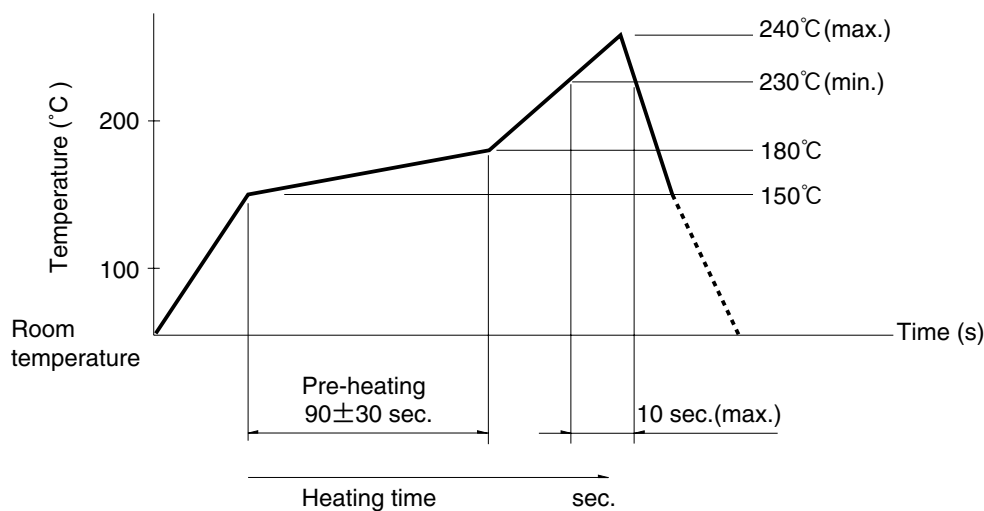
For Compact Flash™

For CMOS Camera Module

Soldering Conditions

Example of Reflow Soldering Condition (Reference)

1. Heating method: Double heating method with infrared heater.
2. Temperature measurement: Thermocouple 0.1 to 0.2 ϕ CA (K) or CC (T).
3. Temperature profile (Surface of products).



Cautions for using this product

1. When soldering terminals, there is a danger that load placed on the terminals may cause rattle, deformation or electrical degradation to occur depending on the conditions. Caution is therefore required.
2. Avoid use of water-soluble soldering flux, since it may corrode the product.
3. Check and conform to reflow soldering requirements under actual mass production conditions.
4. PC board warping may alter the characteristics. Please take this into consideration when designing patterns and layout.
5. The card specifications are provided by the above manufactures. Products by other manufactures may not be compliant with these specifications and are subject to change without prior notice.

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